

2SA2161J

Silicon PNP epitaxial planar type

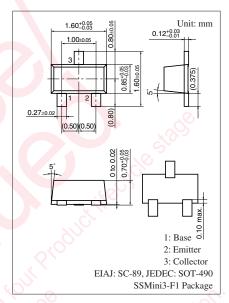
For general amplification Complementary to 2SC6037J

■ Features

- Low collector-emitter saturation voltage V_{CE(sat)}
- SS-Mini type package, allowing downsizing of the equipment and automatic insertion through the tape packing

■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit	
Collector-base voltage (Emitter open)	V_{CBO}	-15	V	
Collector-emitter voltage (Base open)	V _{CEO}	-12	V	
Emitter-base voltage (Collector open)	V _{EBO}	-5	V	
Collector current	I_{C}	-500	mA	
Peak collector current	I_{CP}	-1	A	
Collector power dissipation	P _C	125	mW	
Junction temperature	T_{j}	125	°C	
Storage temperature	T _{stg}	-55 to +125	°CO	



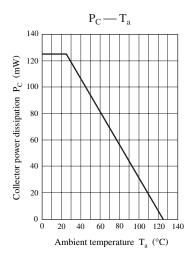
Marking Symbol: 2U

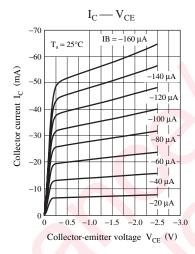
■ Electrical Characteristics $T_a = 25$ °C ± 3°C

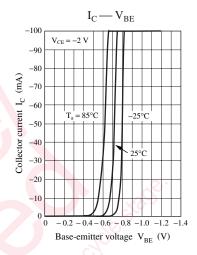
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-base voltage (Emitter open)	V _{CBO}	$I_C = -10 \mu\text{A}, I_E = 0$	-15			V
Collector-emitter voltage (Base open)	V _{CEO}	$I_{\rm C} = -1 \text{ mA}, I_{\rm B} = 0$	-12	25		V
Emitter-base voltage (Collector open)	V_{EBO}	$I_E = -10 \mu\text{A}, I_C = 0$	-5			V
Collector-base cutoff current (Emitter open)	I_{CBO}	$V_{CB} = -15 \text{ V}, I_E = 0$	7.9		- 0.1	μΑ
Forward current transfer ratio	h _{FE}	$V_{CE} = -2 \text{ V}, I_{C} = -10 \text{ mA}$	270		680	_
Collector-emitter saturation voltage	V _{CE(sat)}	$I_C = -200 \text{ mA}, I_B = -10 \text{ mA}$			-250	mV
Transition frequency	f_T	$V_{CB} = -2 \text{ V}, I_E = 10 \text{ mA}, f = 200 \text{ MHz}$		200		MHz
Collector output capacitance (Common base, input open circuited)	C _{ob}	$V_{CB} = 10 \text{ V}, I_E = 0, f = 1 \text{ MHz}$		4.5		pF

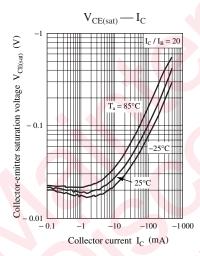
Note) Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

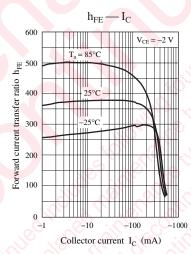
Panasonic

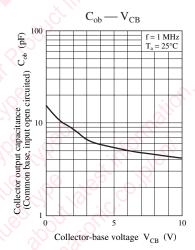












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